

# Dell EMC PowerEdge C6520

## Technical Specifications

## Notes, cautions, and warnings

 **NOTE:** A NOTE indicates important information that helps you make better use of your product.

 **CAUTION:** A CAUTION indicates either potential damage to hardware or loss of data and tells you how to avoid the problem.

 **WARNING:** A WARNING indicates a potential for property damage, personal injury, or death.

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# Technical specifications

The technical and environmental specifications of your system are outlined in this section.

## Topics:

- Sled dimensions
- Chassis weight
- Processor specifications
- PSU specifications
- Supported operating systems
- System battery specifications
- Expansion card riser specifications
- Memory specifications
- Drives
- Storage specifications
- Ports and connectors specifications
- Video specifications
- Environmental specifications

## Sled dimensions

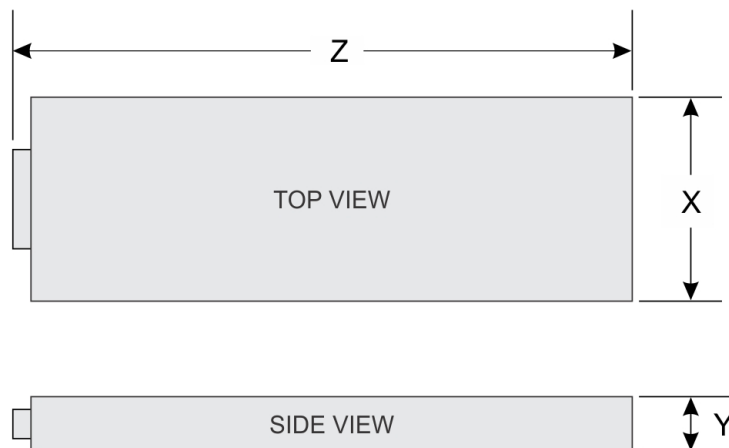


Figure 1. Sled dimensions

Table 1. PowerEdge C6520 sled dimensions

X	Y	Z
174.4 mm (6.86 inches)	40.1 mm (1.58 inches)	570.34 mm (22.45 inches)

# Chassis weight

**Table 2. Chassis weight of the enclosure with the PowerEdge C6520 sleds**

System configuration	Maximum weight (with all sleds and drives)
12 x 3.5-inch	45.6 kg (100.53 lb)
24 x 2.5-inch	41.4 kg (91.27 lb)
System with no backplane	35 kg (77.16 lb)

# Processor specifications

**Table 3. PowerEdge C6520 processor specifications**

Supported processor	Number of processors supported
3 <sup>rd</sup> Generation Intel Xeon Scalable processors with up to 40 cores	two

# PSU specifications

The PowerEdge C6520 system supports up to two AC power supply units (PSUs).

**Table 4. PSU specifications**

PSU	Class	Heat dissipation (maximum)	Frequency	Voltage	AC		Current
					High line	Low line 100–120 V	
2600 W	Platinum Platinum	9750 BTU/hr	50/60 Hz	100 - 240 V autoranging	2600 W (220 - 240 V)	1400 W	16 A
2400 W	Platinum	9000 BTU/hr	50/60 Hz	100 - 240 V autoranging	2400 W (200 - 240 V)	1400 W	16 A
2000 W	Platinum	7500 BTU/hr	50/60 Hz	100 - 240 V autoranging	2000 W (200 - 240 V)	1000 W	11.5 A
1600 W	Platinum	6000 BTU/hr	50/60 Hz	100 - 240 V autoranging	1600 W (200 - 240 V)	800 W	10 A

- NOTE:** The 2600 W PSU with part number 9D4R6 supports only C14-C19 adapter cord.
- NOTE:** This system is also designed to connect to the IT power systems with a phase-to-phase voltage not exceeding 240 V.
- NOTE:** Heat dissipation is calculated using the PSU wattage rating.
- NOTE:** When selecting or upgrading the system configuration, to ensure optimum power utilization, verify the system power consumption with the Dell Energy Smart Solution Advisor available at [Dell.com/ESSA](https://Dell.com/ESSA).

# Supported operating systems

The PowerEdge C6520 system supports the following operating systems:

- Canonical Ubuntu Server LTS
- Citrix Hypervisor
- Microsoft Windows Server with Hyper-V
- Red Hat Enterprise Linux
- SUSE Linux Enterprise Server
- VMware ESXi/vSAN
- CentOS
- Windows Preinstallation Environment (WinPE) 64-bit drivers

For more information, go to [www.dell.com/ossupport](http://www.dell.com/ossupport).

## System battery specifications

The PowerEdge C6520 system supports CR 2032 3.0-V lithium coin cell system battery.

## Expansion card riser specifications

The PowerEdge C6520 system supports up to four PCI express (PCIe) Gen 4 expansion cards.

**Table 5. Expansion card slots supported on the system board**

PCIe slot	Risers	Riser width	PCIe slot height	PCIe slot length	PCIe slot width
Slot 1	Riser 1a	x16 PCIe	Low profile	Half length	x8
Slot 1	Riser 1b with support for SNAP I/O module	x16 PCIe	Low profile	Half length	x8 + x8
Slot 2	Riser 2b	x16 PCIe	Low profile	Half length	x8

**NOTE:** For information on the expansion card installation guidelines, see the system specific *Installation and Service Manual* available at <https://www.dell.com/poweredgemanuals>

## Memory specifications

The PowerEdge C6520 system supports the following memory specifications for optimized operation.

**Table 6. Memory specifications**

DIMM type	DIMM rank	DIMM capacity	Single processor		Dual processors	
			Minimum system capacity	Maximum system capacity	Minimum system capacity	Maximum system capacity
RDIMM	Single rank	8 GB	8 GB	64 GB	16 GB	128 GB
	Dual rank	16 GB	16 GB	128 GB	32 GB	256 GB
		32 GB	32 GB	256 GB	64 GB	512 GB
		64 GB	64 GB	512 GB	128 GB	1 TB
LRDIMM	Quad rank	64 GB	64 GB	512 GB	128 GB	1 TB
		128 GB	128 GB	1 TB	256 GB	2 TB

**Table 7. Memory module sockets**

Memory module sockets	Speed
16, 288-pin	3200 MT/s, 2933 MT/s, 2666 MT/s

# Drives

The PowerEdge C6520 system supports:

- 12 x 3.5-inch SAS/SATA (HDD/SSD) drives
- 24 x 2.5-inch SAS/SATA (HDD/SSD) /NVMe drive.

**Table 8. Maximum number of supported drive options for the PowerEdge C6520 sled**

Maximum number of drives in the sled	Maximum number of drives assigned per sled
12 x 3.5-inch drive systems	Three SAS or SATA drives and SATA SSDs per sled
24 x 2.5-inch Non-NVMe drives configuration	Six SAS or SATA drives and SATA SSDs per sled
8 x 2.5-inch NVMe drives configuration (2 NVMe drives per sled / 8 NVMe drives per chassis)	The NVMe backplane supports either of these configurations: <ul style="list-style-type: none"> <li>• Two NVMe drives and four SAS or SATA drives and SATA SSDs per sled</li> </ul> <b>NOTE:</b> NVMe drives are limited to PCIe Gen3 speed. <ul style="list-style-type: none"> <li>• Six SAS or SATA drives and SATA SSDs per sled</li> </ul>
24 x 2.5-inch NVMe drives configuration	Six NVMe drives per sled
M.2 SATA drive (optional)	The supported capacity of the M.2 SATA card is up to 960 GB <b>NOTE:</b> The M.2 SATA card can be installed on the M.2 riser or on the BOSS card
Micro-SD card (optional) for boot (up to 64 GB)	One on Riser 1a

**NOTE:** For more information about how to hot swap NVMe PCIe SSD U.2 device, see the *Dell Express Flash NVMe PCIe SSD User's Guide* at <https://www.dell.com/support> **Browse all Products > Data Center Infrastructure > Storage Adapters & Controllers > Dell PowerEdge Express Flash NVMe PCIe SSD > Documentation > Manuals and Documents.**

# Storage specifications

The PowerEdge C6520 sled supports.

**Table 9. Storage controller cards for the system**

Internal controllers	External controllers
<ul style="list-style-type: none"> <li>• PERC H745</li> <li>• HBA355i</li> <li>• HBA345</li> <li>• S150</li> <li>• H345</li> <li>• Boot Optimized Storage Subsystem (BOSS-S1): HWRAID 2 x M.2 SSDs</li> <li>• H350</li> <li>• H750</li> </ul>	<ul style="list-style-type: none"> <li>• 12 Gbps SAS Ext. HBA</li> </ul>

**Table 10. Supported RAID options with M.2 SATA drives**

Options	Single M.2 SATA drive without RAID	Dual M.2 SATA drives with hardware RAID
Hardware RAID	No	Yes
RAID Mode	N/A	RAID 1, RAID 0

**Table 10. Supported RAID options with M.2 SATA drives (continued)**

Options	Single M.2 SATA drive without RAID	Dual M.2 SATA drives with hardware RAID
Number of drives supported	1	2
Supported CPUs	CPU 1	CPU 1

**i** | **NOTE:** RAID options are only supported on BOSS cards which support two M.2 SATA drives.

## Ports and connectors specifications

### USB port specifications

The PowerEdge C6520 sled supports USB 3.0 on rear of the system.

### Display port specifications

The PowerEdge C6520 sled supports 1 x Mini-DisplayPort .

### NIC port specifications

The PowerEdge C6520 sled supports one 10/100/1000 Mbps Network Interface Controller (NIC) ports embedded on the LAN on Motherboard (LOM) and integrated on the optional Open Compute Project (OCP) cards.

**Table 11. NIC port specification for the sled**

Feature	Specifications
LOM card	1 GbE
OCP 3.0 card	1 GbE x 4, 10 GbE x 2, 25 GbE x 2, 25 GbE x 4

### iDRAC9 port specifications

The PowerEdge C6520 sled supports 1 x iDRAC Direct port (Micro-AB USB) that is located on the rear of the system.

## Video specifications

The PowerEdge C6520 system supports integrated Matrox G200 graphics controller with 16 MB of video frame buffer.

**Table 12. Supported front video resolution options for the system**

Resolution	Refresh rate (Hz)	Color depth (bits)
1024 x 768	60	8, 16, 32
1280 x 800	60	8, 16, 32
1280 x 1024	60	8, 16, 32
1360 x 768	60	8, 16, 32
1440 x 900	60	8, 16, 32
1600 x 900	60	8, 16, 32
1600 x 1200	60	8, 16, 32

**Table 12. Supported front video resolution options for the system (continued)**

Resolution	Refresh rate (Hz)	Color depth (bits)
1680 x 1050	60	8, 16, 32
1920 x 1080	60	8, 16, 32
1920 x 1200	60	8, 16, 32

## Environmental specifications

**NOTE:** For additional information about environmental certifications, refer to the *Product Environmental Datasheet* located with the Documentation on [www.dell.com/support/home](http://www.dell.com/support/home).

**Table 13. Operational climatic range category A3**

Temperature	Specifications
Allowable continuous operations	
Temperature ranges for altitudes <= 900 m (<= 2953 ft)	5–40°C (41–104°F) with no direct sunlight on the equipment
Humidity percent ranges (non-condensing at all times)	8% RH with -12°C minimum dew point to 85% RH with 24°C (75.2°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/175 m (33.8°F/574 Ft) above 900 m (2953 Ft)

**Table 14. Shared requirements across all categories**

Temperature	Specifications
Allowable continuous operations	
Maximum temperature gradient (applies to both operation and non-operation)	20°C in an hour* (36°F in an hour) and 5°C in 15 minutes (41°F in 15 minutes), 5°C in an hour* (41°F in an hour) for tape <b>NOTE:</b> * - Per ASHRAE thermal guidelines for tape hardware, these are not instantaneous rates of temperature change.
Non-operational temperature limits	-40 to 65°C (-104 to 149°F)
Non-operational humidity limits	5% to 95% RH with 27°C (80.6°F) maximum dew point
Maximum non-operational altitude	12,000 meters (39,370 feet)
Maximum operational altitude	3,048 meters (10,000 feet)

## Maximum vibration specifications

**Table 15. Maximum vibration specifications**

Maximum vibration	Specifications
Operating	0.26 Grms at 5 Hz to 350 Hz (all operation orientations).
Storage	1.88 Grms at 10 Hz to 500 Hz for 15 min (all six sides tested).

## Maximum shock pulse specifications

**Table 16. Maximum shock specifications**

Maximum shock	Specifications
Operating	Six consecutively executed shock pulses 6 G in the positive and negative x, y, z axis for up to 11 ms (four pulses on each side of the system).
Storage	Six consecutively executed shock pulses in the positive and negative x, y, and z axis (one pulse on each side of the system) of 71 G for up to 2 ms.

## Particulate and gaseous contamination specifications

The following table defines the limitations that help avoid any damages to the IT equipment and/or, or both failure from particulate and gaseous contamination. If the levels of particulate or gaseous pollution exceed the specified limitations and results in equipment damage or failure, you must rectify the environmental conditions. Remediation of environmental conditions is the responsibility of the customer.

**Table 17. Particulate contamination specifications**

Particulate contamination	Specifications
Air filtration	<p>Data center air filtration as defined by ISO Class 8 per ISO 14644-1 with a 95% upper confidence limit.</p> <p><b>i</b> <b>NOTE:</b> This condition applies to data center environments only. Air filtration requirements do not apply to IT equipment designed to be used outside a data center, in environments such as an office or factory floor.</p> <p><b>i</b> <b>NOTE:</b> Air entering the data center must have MERV11 or MERV13 filtration.</p>
Conductive dust	<p>Air must be free of conductive dust, zinc whiskers, or other conductive particles.</p> <p><b>i</b> <b>NOTE:</b> This condition applies to data center and non-data center environments.</p>
Corrosive dust	<ul style="list-style-type: none"> <li>Air must be free of corrosive dust.</li> <li>Residual dust present in the air must have a deliquescent point less than 60% relative humidity.</li> </ul> <p><b>i</b> <b>NOTE:</b> This condition applies to data center and non-data center environments.</p>

**Table 18. Gaseous contamination specifications**

Gaseous contamination	Specifications
Copper Coupon Corrosion rate	<300 Å/month per Class G1 as defined by ANSI/ISA71.04-2013
Silver Coupon Corrosion rate	<200 Å/month as defined by ANSI/ISA71.04-2013

**i** **NOTE:** Maximum corrosive contaminant levels measured at ≤50% relative humidity.

## Thermal restrictions

**i** **NOTE:**

1. Not available: Indicates that the configuration is not offered by Dell EMC.

2. Not supported: Indicates that the configuration is not thermally supported.

**NOTE:** All components including the DIMMs, communication cards, M.2 SATA, and PERC cards can be supported with sufficient thermal margin if the ambient temperature is equal to or below the maximum continuous operating temperature listed in these tables.

**NOTE:** Some of the system hardware configurations require a lowered upper temperature limit. For more information about the operating temperature requirement, contact technical support.

**NOTE:** Some configurations require a lower ambient temperature. For more information, see the following tables.

The following tables list key restrictions on ambient temperature based on which CPU is configured in the system. All inlet temperatures that are provided below are in continuous degrees centigrade.

**Table 19. Maximum continuous operating temperature for dual processor with 2.5-inch direct / 2.5-inch NVMe drive configuration- Air cooled**

Processors	TDP (W)	Cores	6 x drives/ sled	4 x drives/sled	2 x drives/sled	1 x drive/sled	No BP
8380	270	40	Not supported	Not supported	Not supported	Not supported	Not supported
8368	270	38	Not supported	Not supported	Not supported	Not supported	Not supported
8368Q	270	38	Not supported	Not supported	Not supported	Not supported	Not supported
8362	265	32	Not supported	Not supported	Not supported	Not supported	Not supported
8360Y	250	36	Not supported	Not supported	Not supported	Not supported	Not supported
8358	250	32	Not supported	Not supported	Not supported	Not supported	Not supported
8358P	240	32	Not supported	Not supported	Not supported	Not supported	20
6348	235	28	Not supported	Not supported	Not supported	Not supported	20
6342	230	24	Not supported	Not supported	Not supported	20	20
8352Y	205	32	20	20	25	25	25
8352S	205	32	20	20	25	25	25
6338	205	32	20	20	25	25	25
6330	205	28	20	20	25	25	25
6354	205	18	Not supported	20	20	20	25
6346	205	16	Not supported	20	20	20	25
8352V	195	36	20	20	25	25	25
8352M	185	32	20*	20*	25	25	25
6338N	185	32	20*	20*	25	25	25
5320	185	26	20*	20*	25	25	25
6336Y	185	24	20*	20*	25	25	25
6326	185	16	20*	20*	25	25	25
6330N	165	28	25	25*	25*	25*	25*
6338T	165	24	25	25*	25*	25*	25*
5318Y	165	24	25	25*	25*	25*	25*

**Table 19. Maximum continuous operating temperature for dual processor with 2.5-inch direct / 2.5-inch NVMe drive configuration- Air cooled (continued)**

Processors	TDP (W)	Cores	6 x drives/sled	4 x drives/sled	2 x drives/sled	1 x drive/sled	No BP
5318S	165	24	25	25*	25*	25*	25*
6334	165	8	25	25*	25*	25*	25*
5318N	150	24	25*	30	30	30	30*
5320T	150	20	25*	30	30	30	30*
4316	150	20	25*	30	30	30	30*
5317	150	12	25*	30	30	30	30*
5315Y	140	8	30	30	30*	30*	30*
4314	135	16	30*	30*	30*	30*	30*
4310	120	12	35	35	35	35	35
4310T	105	10	35	35	35	35	35
4309Y	105	8	35	35	35	35	35

**NOTE:**

- Data with \* mark means it can have a temperature offset by +5°C, if using extended processor 1 with HSK on this configuration.
- H745 is not supported with processor TDP > 185 W.
- Additional thermal restrictions are required for PCIE > 25 Watts, 128GB LRDIMM and GPU configuration.

**Table 20. Maximum continuous operating temperature for single processor with 2.5-inch direct drive configuration for processor 1 - Air cooled**

Processors	TDP (W)	Cores	6 x drives/sled	4 x drives/sled	2 x drives/ sled	1 x drive/ sled	No BP
8380	270	40	20	20	20	20	25
8368	270	38	20	20	25	25	25
8368Q	270	38	Not supported	Not supported	Not supported	Not supported	Not supported
8362	265	32	20	20	25	25	25
8360Y	250	36	20	20	25	25	25
8358	250	32	20	20	25	25	25
8358P	240	32	20	20	25	25	25
6348	235	28	25	25	25	25	30
6342	230	24	25	25	25	25	30
8351N	225	36	20	20	25	25	25
8352Y	205	32	30	30	35	35	35
6314U	205	32	30	30	35	35	35
8352S	205	32	30	30	35	35	35
6338	205	32	30	30	35	35	35
6330	205	28	30	30	35	35	35
6354	205	18	25	25	30	30	30

**Table 20. Maximum continuous operating temperature for single processor with 2.5-inch direct drive configuration for processor 1 - Air cooled (continued)**

Processors	TDP (W)	Cores	6 x drives/ sled	4 x drives/ sled	2 x drives/ sled	1 x drive/ sled	No BP
6346	205	16	25	25	30	30	30
8352V	195	36	30	30	30	30	35
8352M	185	32	35	35	35	35	35
6338N	185	32	35	35	35	35	35
5320	185	26	35	35	35	35	35
6336Y	185	24	35	35	35	35	35
6312U	185	24	35	35	35	35	35
6326	185	16	35	35	35	35	35
6330N	165	28	35	35	35	35	35
6338T	165	24	35	35	35	35	35
5318Y	165	24	35	35	35	35	35
5318S	165	24	35	35	35	35	35
6334	165	8	35	35	35	35	35
5318N	150	24	35	35	35	35	35
5320T	150	20	35	35	35	35	35
4316	150	20	35	35	35	35	35
5317	150	12	35	35	35	35	35
5315Y	140	8	35	35	35	35	35
4314	135	16	35	35	35	35	35
4310	120	12	35	35	35	35	35
4310T	105	10	35	35	35	35	35
4309Y	105	8	35	35	35	35	35

**i** | **NOTE:** Additional thermal restrictions are required for PCIE > 25 Watts, 128GB LRDIMM and GPU configuration.

**Table 21. Maximum continuous operating temperature for dual processor with 2.5-inch Pure NVMe drive configuration- Air cooled**

Processors	TDP (W)	Cores	6 x drives/sled	4 x drives/sled	2 x drives/sled	1 x drive/sled
8380	270	40	Not supported	Not supported	Not supported	Not supported
8368	270	38	Not supported	Not supported	Not supported	Not supported
8368Q	270	38	Not supported	Not supported	Not supported	Not supported
8362	265	32	Not supported	Not supported	Not supported	Not supported
8360Y	250	36	Not supported	Not supported	Not supported	Not supported
8358	250	32	Not supported	Not supported	Not supported	Not supported
8358P	240	32	Not supported	Not supported	Not supported	Not supported
6348	235	28	Not supported	Not supported	Not supported	Not supported
6342	230	24	Not supported	Not supported	Not supported	20

**Table 21. Maximum continuous operating temperature for dual processor with 2.5-inch Pure NVMe drive configuration- Air cooled (continued)**

Processors	TDP (W)	Cores	6 x drives/sled	4 x drives/sled	2 x drives/sled	1 x drive/sled
8352Y	205	32	20	20	25	25
8352S	205	32	20	20	25	25
6338	205	32	20	20	25	25
6330	205	28	20	20	25	25
6354	205	18	Not supported	Not supported	20	20
6346	205	16	Not supported	Not supported	20	20
8352V	195	36	20	20	25	25
8352M	185	32	20	20	25	25
6338N	185	32	20	20	25	25
5320	185	26	20	20	25	25
6336Y	185	24	20	20	25	25
6326	185	16	20	20	25	25
6330N	165	28	20*	20*	25*	25*
6338T	165	24	20*	20*	25*	25*
5318Y	165	24	20*	20*	25*	25*
5318S	165	24	20*	20*	25*	25*
6334	165	8	20*	20*	25*	25*
5318N	150	24	25	25	30	30
5320T	150	20	25	25	30	30
4316	150	20	25	25	30	30
5317	150	12	25	25	30	30
5315Y	140	8	25*	25*	30*	30*
4314	135	16	25*	25*	30*	30*
4310	120	12	30	30	35	35
4310T	105	10	30*	30*	35	35
4309Y	105	8	30*	30*	35	35

**Table 22. Maximum continuous operating temperature for dual processor with 3.5-inch direct drive configuration- Air cooled**

Processors	TDP (W)	Cores	3 x drives/sled	2 x drives/sled	1 x drive/sled
8380	270	40	Not supported	Not supported	Not supported
8368	270	38	Not supported	Not supported	Not supported
8368Q	270	38	Not supported	Not supported	Not supported
8362	265	32	Not supported	Not supported	Not supported
8360Y	250	36	Not supported	Not supported	Not supported
8358	250	32	Not supported	Not supported	Not supported
8358P	240	32	Not supported	Not supported	Not supported
6348	235	28	Not supported	Not supported	Not supported

**Table 22. Maximum continuous operating temperature for dual processor with 3.5-inch direct drive configuration- Air cooled (continued)**

Processors	TDP (W)	Cores	3 x drives/sled	2 x drives/sled	1 x drive/sled
6342	230	24	Not supported	Not supported	Not supported
8351N	225	36	Not supported	Not supported	Not supported
8352Y	205	32	Not supported	Not supported	Not supported
6314U	205	32	Not supported	Not supported	Not supported
8352S	205	32	Not supported	Not supported	Not supported
6338	205	32	Not supported	Not supported	Not supported
6330	205	28	Not supported	Not supported	Not supported
6354	205	18	Not supported	Not supported	Not supported
6346	205	16	Not supported	Not supported	Not supported
8352V	195	36	Not supported	Not supported	Not supported
8352M	185	32	Not supported	Not supported	Not supported
6338N	185	32	Not supported	Not supported	Not supported
5320	185	26	Not supported	Not supported	Not supported
6336Y	185	24	Not supported	Not supported	Not supported
6312U	185	24	Not supported	Not supported	Not supported
6326	185	16	Not supported	Not supported	Not supported
6330N	165	28	Not supported	Not supported	20
6338T	165	24	Not supported	Not supported	20
5318Y	165	24	Not supported	Not supported	20
5318S	165	24	Not supported	Not supported	20
6334	165	8	Not supported	Not supported	20
5318N	150	24	Not supported	Not supported	20
5320T	150	20	Not supported	Not supported	20
4316	150	20	Not supported	Not supported	20
5317	150	12	Not supported	Not supported	20
5315Y	140	8	Not supported	20	20*
4314	135	16	Not supported	20*	20*
4310	120	12	20	25	25
4310T	105	10	25	30	30
4309Y	105	8	25	30	30

**Table 23. Maximum continuous operating temperature for single processor with 3.5-inch direct drive configuration- Air cooled**

Processors	TDP (W)	Cores	3 x drives/sled	2 x drives/sled	1 x drive/sled
8380	270	40	Not supported	Not supported	Not supported
8368	270	38	Not supported	Not supported	Not supported
8368Q	270	38	Not supported	Not supported	Not supported
8362	265	32	Not supported	Not supported	Not supported

**Table 23. Maximum continuous operating temperature for single processor with 3.5-inch direct drive configuration- Air cooled (continued)**

<b>Processors</b>	<b>TDP (W)</b>	<b>Cores</b>	<b>3 x drives/sled</b>	<b>2 x drives/sled</b>	<b>1 x drive/sled</b>
8360Y	250	36	Not supported	Not supported	Not supported
8358	250	32	Not supported	Not supported	Not supported
8358P	240	32	Not supported	Not supported	20
6348	235	28	Not supported	20	20
6342	230	24	Not supported	20	20
8351N	225	36	Not supported	Not supported	20
8352Y	205	32	20	25	25
6314U	205	32	20	25	25
8352S	205	32	20	25	25
6338	205	32	20	25	25
6330	205	28	20	25	25
6354	205	18	Not supported	20	25
6346	205	16	Not supported	20	25
8352V	195	36	20	25	25
8352M	185	32	25	30	30
6338N	185	32	25	30	30
5320	185	26	25	30	30
6336Y	185	24	25	30	30
6312U	185	24	25	30	30
6326	185	16	25	30	30
6330N	165	28	25	30	30
6338T	165	24	25	30	30
5318Y	165	24	25	30	30
5318S	165	24	25	30	30
6334	165	8	25	30	30
5318N	150	24	30	35	35
5320T	150	20	30	35	35
4316	150	20	30	35	35
5317	150	12	30	35	35
5315Y	140	8	30	35	35
4314	135	16	30	35	35
4310	120	12	30	35	35
4310T	105	10	35	35	35
4309Y	105	8	35	35	35

**Table 24. Maximum continuous operating temperature for dual processor with 2.5-inch direct / 2.5-inch NVMe drive configuration- Liquid cooled**

Processors	TDP (W)	Cores	6 x drives/ sled	4 x drives/ sled	2 x drives/ sled	1 x drive/ sled	No BP
8380	270	40	35	35	35	35	35
8368	270	38	35	35	35	35	35
8368Q	270	38	35	35	35	35	35
8362	265	32	35	35	35	35	35
8360Y	250	36	35	35	35	35	35
8358	250	32	35	35	35	35	35
8358P	240	32	35	35	35	35	35
6348	235	28	35	35	35	35	35
6342	230	24	35	35	35	35	35
8352Y	205	32	35	35	35	35	35
8352S	205	32	35	35	35	35	35
6338	205	32	35	35	35	35	35
6330	205	28	35	35	35	35	35
6354	205	18	35	35	35	35	35
6346	205	16	35	35	35	35	35
8352V	195	36	35	35	35	35	35
8352M	185	32	35	35	35	35	35
6338N	185	32	35	35	35	35	35
5320	185	26	35	35	35	35	35
6336Y	185	24	35	35	35	35	35
6326	185	16	35	35	35	35	35
6330N	165	28	35	35	35	35	35
6338T	165	24	35	35	35	35	35
5318Y	165	24	35	35	35	35	35
5318S	165	24	35	35	35	35	35
6334	165	8	35	35	35	35	35
5318N	150	24	35	35	35	35	35
5320T	150	20	35	35	35	35	35
4316	150	20	35	35	35	35	35
5317	150	12	35	35	35	35	35
5315Y	140	8	35	35	35	35	35
4314	135	16	35	35	35	35	35
4310	120	12	35	35	35	35	35
4310T	105	10	35	35	35	35	35
4309Y	105	8	35	35	35	35	35

**NOTE:** Additional thermal restrictions are required for PCIE > 25 Watts, 128GB LRDIMM and GPU configuration.

**Table 25. Maximum continuous operating temperature for dual processor with 2.5-inch Pure NVMe drive configuration- Liquid cooled**

Processors	TDP (W)	Cores	6 x drives/ sled	4 x drives/ sled	2 x drives/ sled	1 x drive/ sled
8380	270	40	35	35	35	35
8368	270	38	35	35	35	35
8368Q	270	38	35	35	35	35
8362	265	32	35	35	35	35
8360Y	250	36	35	35	35	35
8358	250	32	35	35	35	35
8358P	240	32	35	35	35	35
6348	235	28	35	35	35	35
6342	230	24	35	35	35	35
8352Y	205	32	35	35	35	35
8352S	205	32	35	35	35	35
6338	205	32	35	35	35	35
6330	205	28	35	35	35	35
6354	205	18	35	35	35	35
6346	205	16	35	35	35	35
8352V	195	36	35	35	35	35
8352M	185	32	35	35	35	35
6338N	185	32	35	35	35	35
5320	185	26	35	35	35	35
6336Y	185	24	35	35	35	35
6326	185	16	35	35	35	35
6330N	165	28	35	35	35	35
6338T	165	24	35	35	35	35
5318Y	165	24	35	35	35	35
5318S	165	24	35	35	35	35
6334	165	8	35	35	35	35
5318N	150	24	35	35	35	35
5320T	150	20	35	35	35	35
4316	150	20	35	35	35	35
5317	150	12	35	35	35	35
5315Y	140	8	35	35	35	35
4314	135	16	35	35	35	35
4310	120	12	35	35	35	35
4310T	105	10	35	35	35	35

**Table 25. Maximum continuous operating temperature for dual processor with 2.5-inch Pure NVMe drive configuration- Liquid cooled (continued)**

Processors	TDP (W)	Cores	6 x drives/ sled	4 x drives/ sled	2 x drives/ sled	1 x drive/ sled
4309Y	105	8	35	35	35	35

**i** **NOTE:** Additional thermal restrictions are required for PCIE > 25 Watts, 128GB LRDIMM and GPU configuration.

**Table 26. Maximum continuous operating temperature for dual processor with 3.5-inch direct drive configuration- Liquid cooled**

Processors	TDP (W)	Cores	3 x drives/sled	2 x drives/sled	1 x drive/sled
8380	270	40	35	35	35
8368	270	38	35	35	35
8368Q	270	38	35	35	35
8362	265	32	35	35	35
8360Y	250	36	35	35	35
8358	250	32	35	35	35
8358P	240	32	35	35	35
6348	235	28	35	35	35
6342	230	24	35	35	35
8352Y	205	32	35	35	35
8352S	205	32	35	35	35
6338	205	32	35	35	35
6330	205	28	35	35	35
6354	205	18	35	35	35
6346	205	16	35	35	35
8352V	195	36	35	35	35
8352M	185	32	35	35	35
6338N	185	32	35	35	35
5320	185	26	35	35	35
6336Y	185	24	35	35	35
6326	185	16	35	35	35
6330N	165	28	35	35	35
6338T	165	24	35	35	35
5318Y	165	24	35	35	35
5318S	165	24	35	35	35
6334	165	8	35	35	35
5318N	150	24	35	35	35
5320T	150	20	35	35	35
4316	150	20	35	35	35
5317	150	12	35	35	35

**Table 26. Maximum continuous operating temperature for dual processor with 3.5-inch direct drive configuration- Liquid cooled (continued)**

Processors	TDP (W)	Cores	3 x drives/sled	2 x drives/sled	1 x drive/sled
5315Y	140	8	35	35	35
4314	135	16	35	35	35
4310	120	12	35	35	35
4310T	105	10	35	35	35
4309Y	105	8	35	35	35

**NOTE:** Additional thermal restrictions are required for PCIe > 25 Watts, 128GB LRDIMM and GPU configuration.

### ASHRAE A3 Configuration Restriction

**Table 27. ASHRAE A3 Configuration Restriction**

Liquid cooled	Air Cooled
<ul style="list-style-type: none"> <li>• NVMe SSD is not supported.</li> <li>• LRDIMM is not supported.</li> <li>• PCIe cards greater than 25 W are not supported.</li> <li>• GPU card is not supported.</li> <li>• 3.5-inch drive configuration is not supported.</li> </ul>	<ul style="list-style-type: none"> <li>• NVMe SSD is not supported.</li> <li>• LRDIMM is not supported.</li> <li>• PCIe cards greater than 25W are not supported.</li> <li>• GPU card is not supported.</li> <li>• 3.5-inch drive configuration is not supported.</li> <li>• For 1P sled, maximum supported CPU TDP is 150 W.</li> <li>• For 2P sled, maximum supported CPU TDP is 105 W..</li> </ul>